

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
60V	3.3mΩ@10V	140A

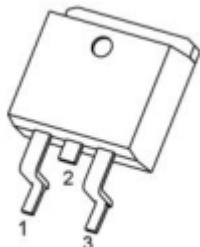
Feature

- Fast Switching
- Low Gate Charge and Rdson
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

Applications

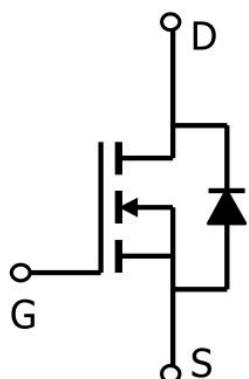
- DC-DC Converters
- Power Management

Package

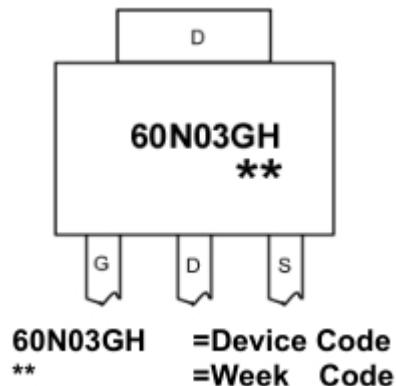


TO-263(G:1 D:2 S:3)

Circuit diagram



Marking



Absolute maximum ratings

($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹ ($T_c=25^\circ\text{C}$)	I_D	140	A
Pulsed Drain Current ²	I_{DM}	560	A
Single Pulse Avalanche Energy ³	E_{AS}	961	mJ
Total Power Dissipation ⁴ ($T_c=25^\circ\text{C}$)	P_D	140	W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	0.89	$^\circ\text{C}/\text{W}$
Storage Temperature Range	T_{STG}	-55~ +150	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55~ +150	$^\circ\text{C}$

Electrical characteristics

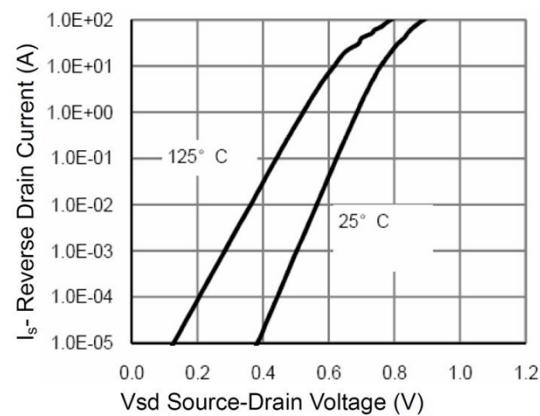
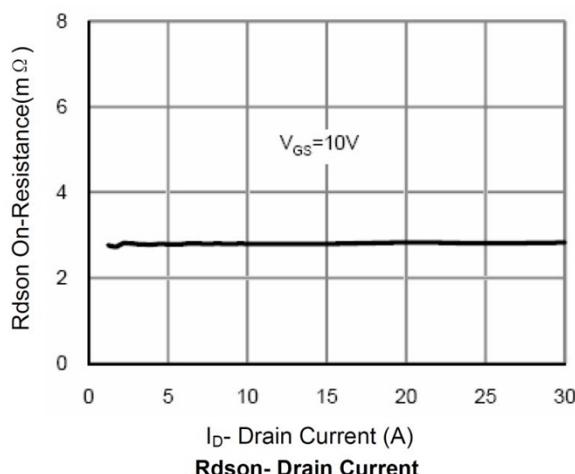
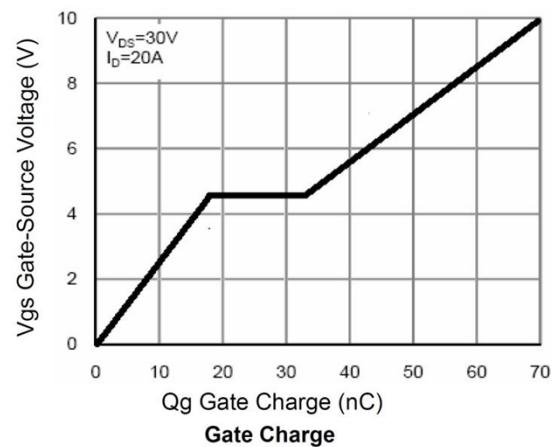
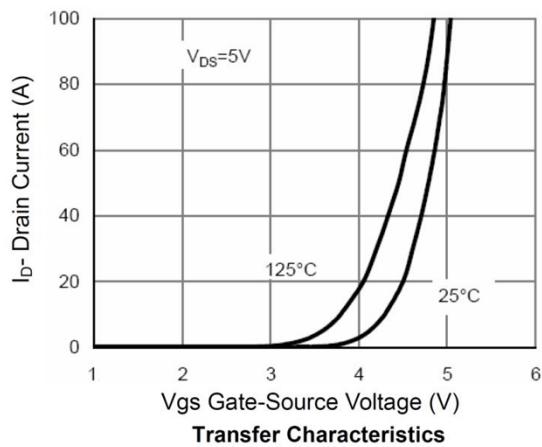
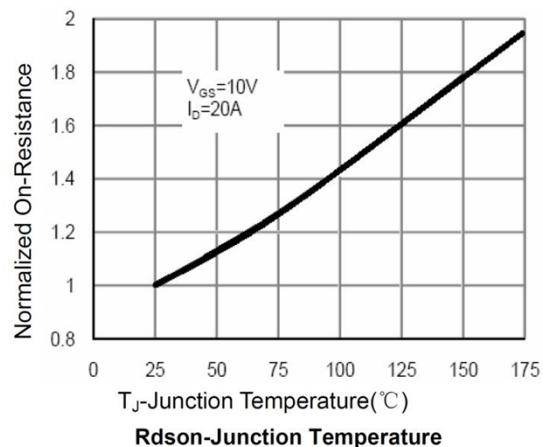
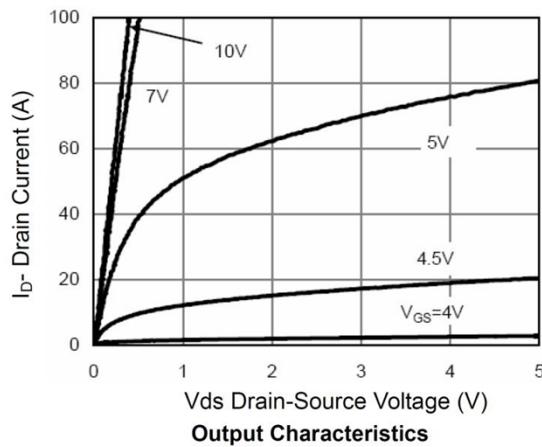
($T_A=25^\circ\text{C}$, unless otherwise noted)

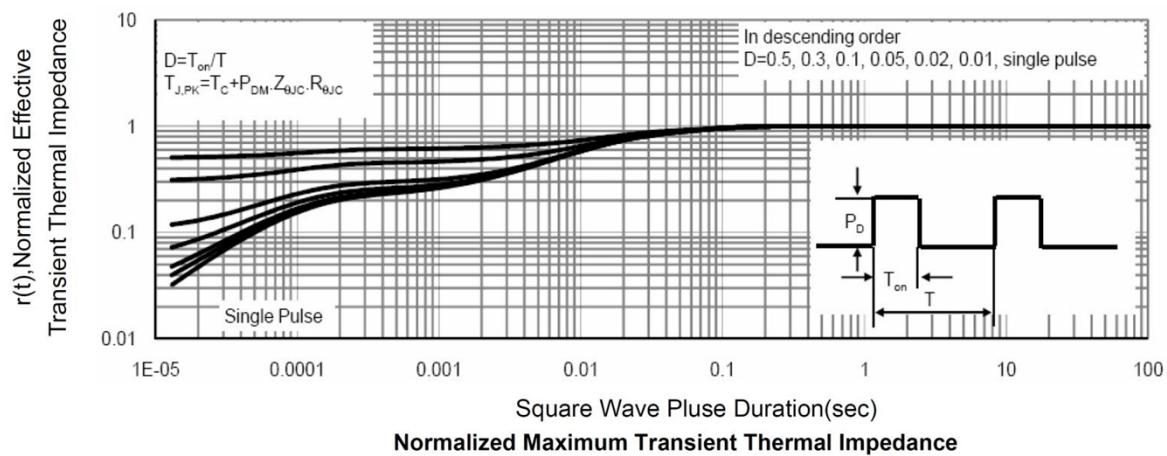
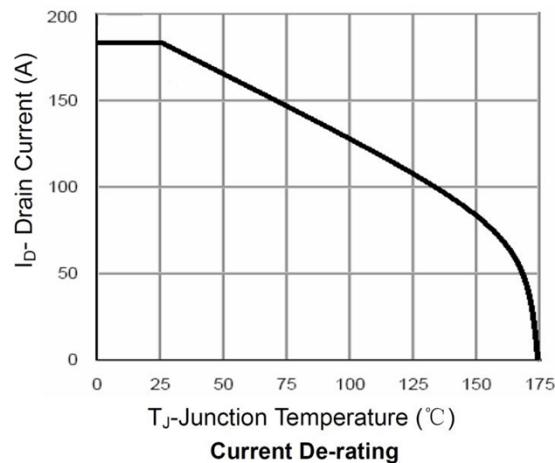
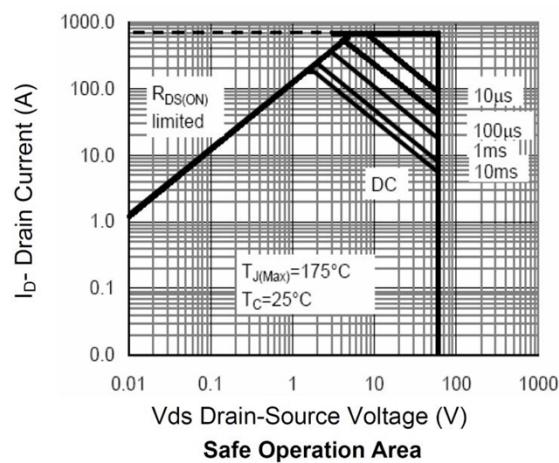
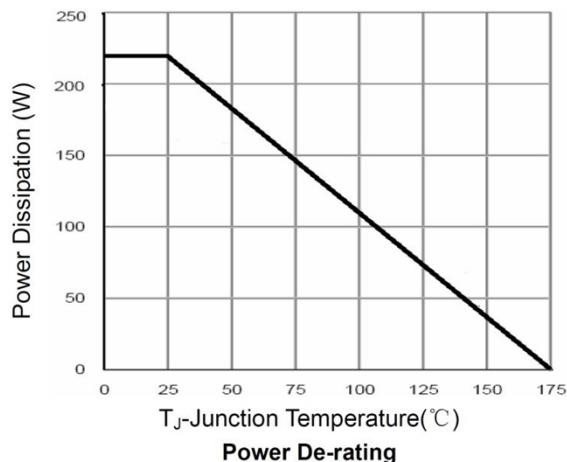
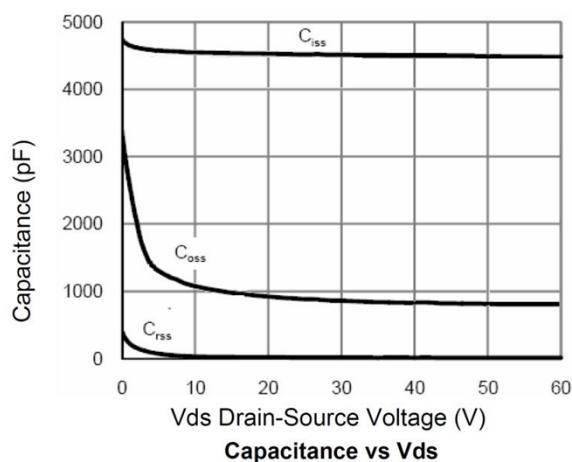
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$\text{BV}_{(\text{BR})\text{DSS}}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	60			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = 48\text{V}, V_{GS} = 0\text{V}$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			± 100	μA
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0	2.5	4.0	V
Static Drain-Source On-Resistance ²	$R_{DS(\text{on})}$	$V_{GS} = 10\text{V}, I_D = 20\text{A}$		3.3	4.2	$\text{m}\Omega$
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=30\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$		4250		pF
Output Capacitance	C_{oss}			975		
Reverse Transfer Capacitance	C_{rss}			41		
Switching Characteristics						
Total Gate Charge	Q_g	$V_{DS}=30\text{V}, V_{GS}=10\text{V}, I_D = 20\text{A}$		68		pF
Gate-Source Charge	Q_{gs}			19		
Gate-Drain Charge	Q_{gd}			14		
Turn-on Delay Time	$T_{d(\text{on})}$	$V_{DD}=30\text{V}, V_{GS}=10\text{V}, R_G = 4.7\Omega, I_D = 20\text{A}$		6		nS
Turn-on Rise Time	T_r			12		
Turn-off Delay Time	$T_{d(\text{off})}$			24		
Turn-off Fall Time	T_f			5		
Diode Characteristics						
Diode Forward Voltage ²	V_{SD}	$V_{GS}=0\text{V}, I_S=1\text{A}, T_j=25^\circ\text{C}$			1.2	V

Note :

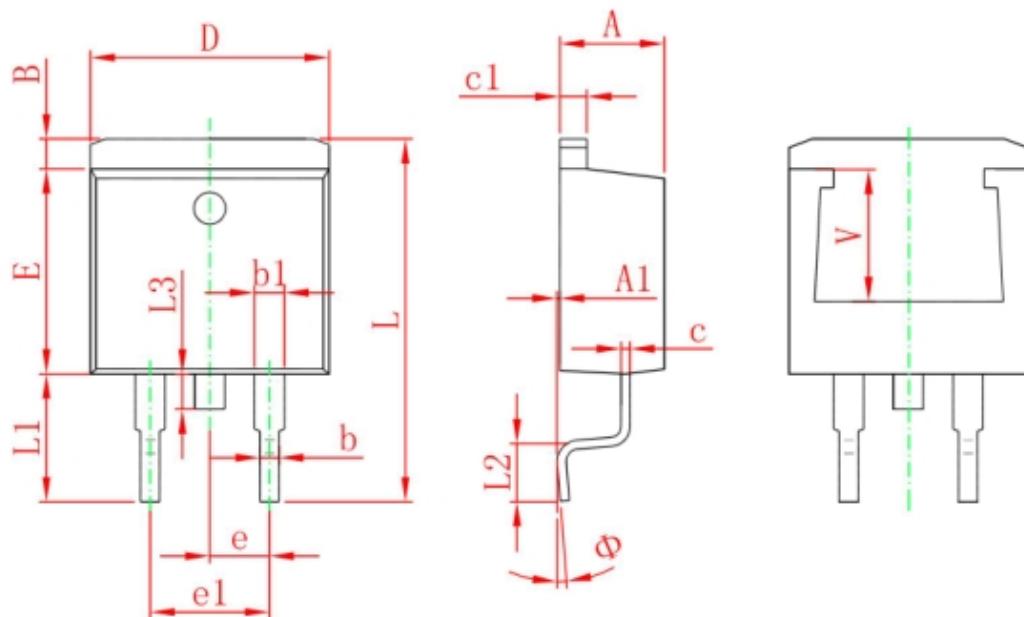
1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is $V_{DD}=30\text{V}, V_{GS}=10\text{V}, L=0.5\text{mH}, R_G=25\Omega$
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics





TO-263 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.470	4.670	0.176	0.184
A1	0.000	0.150	0.000	0.006
B	1.120	1.420	0.044	0.056
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
E	8.500	8.900	0.335	0.350
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
L	14.940	15.500	0.588	0.610
L1	4.950	5.450	0.195	0.215
L2	2.340	2.740	0.092	0.108
L3	1.300	1.700	0.051	0.067
Φ	0°	8°	0°	8°
V	5.600 REF.		0.220 REF.	